

| L Number | Hits | Search Text | DB | Time stamp |
|-------------|---------|--|---|------------------|
| 1 | 2834734 | ((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/22 06:40 |
| 2 | 271932 | ((ceramic insulated insulating) with (carrier substrate)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/22 06:41 |
| 3 | 97251 | ((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) with ((ceramic insulated insulating) with (carrier substrate)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/22 06:41 |
| 4 | 117982 | ((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) same ((ceramic insulated insulating) with (carrier substrate)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/22 06:42 |
| 5 | 5573 | wire same (((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) with ((ceramic insulated insulating) with (carrier substrate))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/22 06:42 |
| 6 | 7758 | wire same (((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) same ((ceramic insulated insulating) with (carrier substrate))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/22 06:43 |
| 7 | 1266 | (resin encapsulated encapsulation encapsulating epoxy) same (wire same (((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) with ((ceramic insulated insulating) with (carrier substrate)))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/22 06:44 |
| 8 | 1884 | (resin encapsulated encapsulation encapsulating epoxy) same (wire same (((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) same ((ceramic insulated insulating) with (carrier substrate)))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/22 06:44 |
| 9 | 330 | (expose exposing exposed external externally) same ((resin encapsulated encapsulation encapsulating epoxy) same (wire same (((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) with ((ceramic insulated insulating) with (carrier substrate))))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/22 06:45 |
| 10 | 498 | (expose exposing exposed external externally) same ((resin encapsulated encapsulation encapsulating epoxy) same (wire same (((semiconductor die chip mosfet schottky diode ic (integrated adj circuit))) same ((ceramic insulated insulating) with (carrier substrate))))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/03/22 06:45 |